

## 1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in IITO220 internally insulated plastic package intended for use in applications requiring very high inrush current capability, high thermal cycling performance and high junction temperature capability ( $T_{j(max)} = 150\text{ °C}$ ).

## 2. Features and benefits

- High junction operating temperature capability ( $T_{j(max)} = 150\text{ °C}$ )
- High bidirectional blocking voltage capability
- Very high current surge capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- Internally insulated package
- Isolated mounting base with 2500 V (RMS) isolation

## 3. Applications

- High voltage capability
- Protection circuit in Power Supplies for Consumer / Industrial / Medical Equipment
- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation

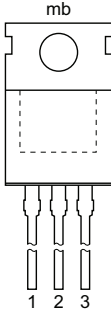

## 4. Quick reference data

Table 1. Quick reference data

| Symbol                         | Parameter                            | Conditions  | Notes | Values     |     |      | Unit       |
|--------------------------------|--------------------------------------|---|-------|------------|-----|------|------------|
| $V_{DRM}$                      | repetitive peak off-state voltage    |   |       | 800        |     |      | V          |
| $I_{T(RMS)}$                   | RMS on-state current                 | half sine wave; $T_{mb} \leq 85\text{ °C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>    |       | 50         |     |      | A          |
| $I_{TSM}$                      | non-repetitive peak on-state current | half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>    |       | 500        |     |      | A          |
|                                |                                      | half sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$  |       | 550        |     |      | A          |
| $T_j$                          | junction temperature                 |   |       | -40 to 150 |     |      | °C         |
| Symbol                         | Parameter                            | Conditions  | Notes | Min        | Typ | Max  | Unit       |
| <b>Static characteristics</b>  |                                      |   |       |            |     |      |            |
| $I_{GT}$                       | gate trigger current                 | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>                                  |       | -          | -   | 15   | mA         |
| $I_H$                          | holding current                      | $V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>   |       | -          | -   | 60   | mA         |
| $V_T$                          | on-state voltage                     | $I_T = 100\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>   |       | -          | -   | 1.65 | V          |
| <b>Dynamic characteristics</b> |                                      |   |       |            |     |      |            |
| $dV_D/dt$                      | rate of rise of off-state voltage    | $V_{DM} = 536\text{ V}$ ; $T_j = 150\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit |       | 500        | -   | -    | V/ $\mu$ s |

## 5. Pinning information

**Table 2. Pinning information**

| Pin | Symbol | Description             | Simplified outline  | Graphic symbol  |
|-----|--------|-------------------------|---|---|
| 1   | K      | cathode                 |  |  |
| 2   | A      | anode                   |   |   |
| 3   | G      | gate                    |   |   |
| mb  | n.c.   | mounting base; isolated |   |   |

## 6. Ordering information

**Table 3. Ordering information**

| Type number | Package Name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|-------------|--------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| TYN50Y-800T | IITO220      | TYN50Y-800TQ          | Tube           | 50                     | SOT78D          | 07-July-2010       |

## 7. Marking

**Table 4. Marking codes**

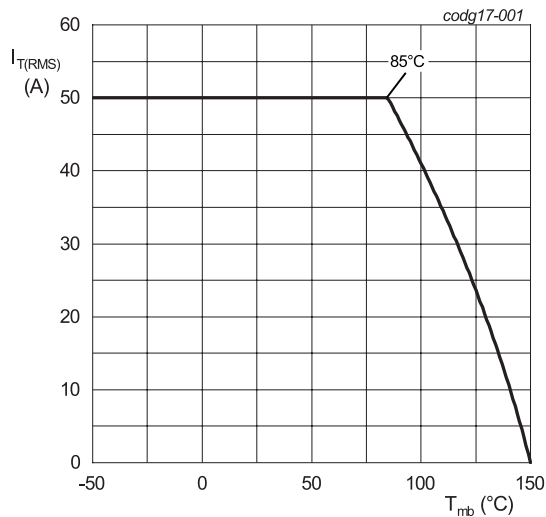
| Type number | Marking codes  |
|-------------|----------------|
| TYN50Y-800T | TYN50Y<br>800T |

## 8. Limiting values

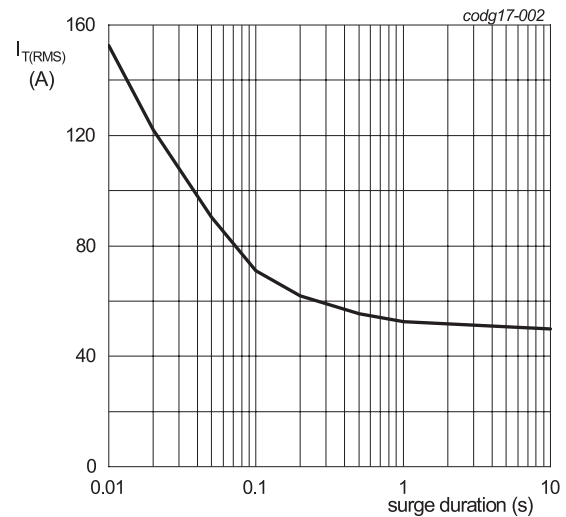
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions  | Notes | Values     | Unit             |
|--------------|--------------------------------------|---|-------|------------|------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |   |       | 800        | V                |
| $V_{RRM}$    | repetitive peak reverse voltage      |   |       | 800        | V                |
| $I_{T(AV)}$  | average on-state current             | half sine wave; $T_{mb} \leq 85\text{ °C}$ ;  |       | 32         | A                |
| $I_{T(RMS)}$ | RMS on-state current                 | half sine wave; $T_{mb} \leq 85\text{ °C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>        |       | 50         | A                |
| $I_{TSM}$    | non-repetitive peak on-state current | half sine wave; $T_{j(\text{init})} = 25\text{ °C}$ ; $t_p = 10\text{ ms}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> |       | 500        | A                |
|              |                                      | half sine wave; $T_{j(\text{init})} = 25\text{ °C}$ ; $t_p = 8.3\text{ ms}$   |       | 550        | A                |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ ms}$ ; sine-wave pulse  |       | 1250       | A <sup>2</sup> s |
| $di_T/dt$    | rate of rise of on-state current     | $I_G = 30\text{ mA}$  |       | 150        | A/ $\mu$ s       |
| $I_{GM}$     | peak gate current                    |   |       | 5          | A                |
| $V_{GM}$     | peak gate voltage                    |   |       | 5          | V                |
| $P_{GM}$     | peak gate power                      |   |       | 20         | W                |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period   |       | 1          | W                |
| $T_{stg}$    | storage temperature                  |   |       | -40 to 150 | °C               |
| $T_j$        | junction temperature                 |   |       | -40 to 150 | °C               |

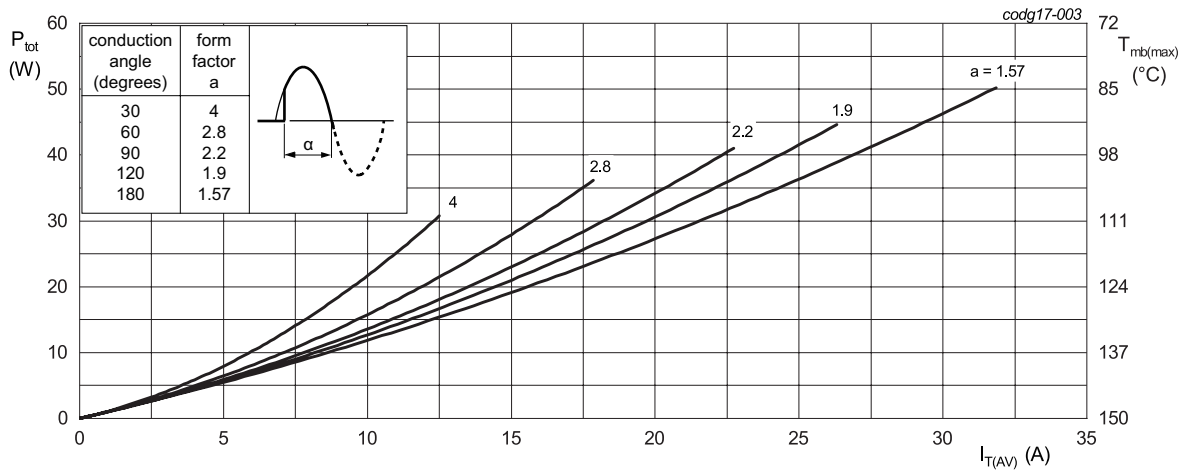


**Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values**



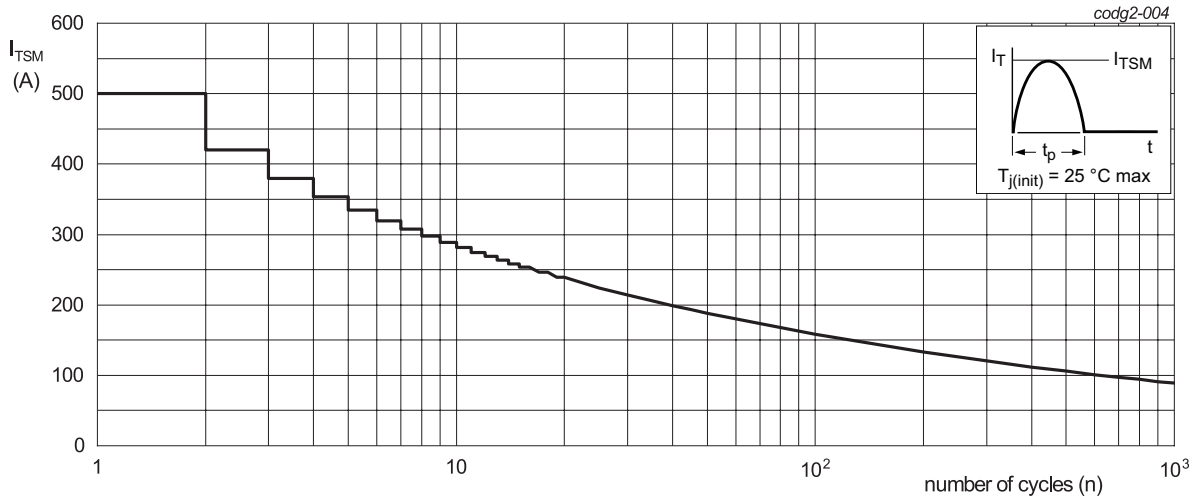
$f = 50\text{ Hz}$ ;  $T_{mb} = 85\text{ °C}$

**Fig. 2. RMS on-state current as a function of surge duration; maximum values**



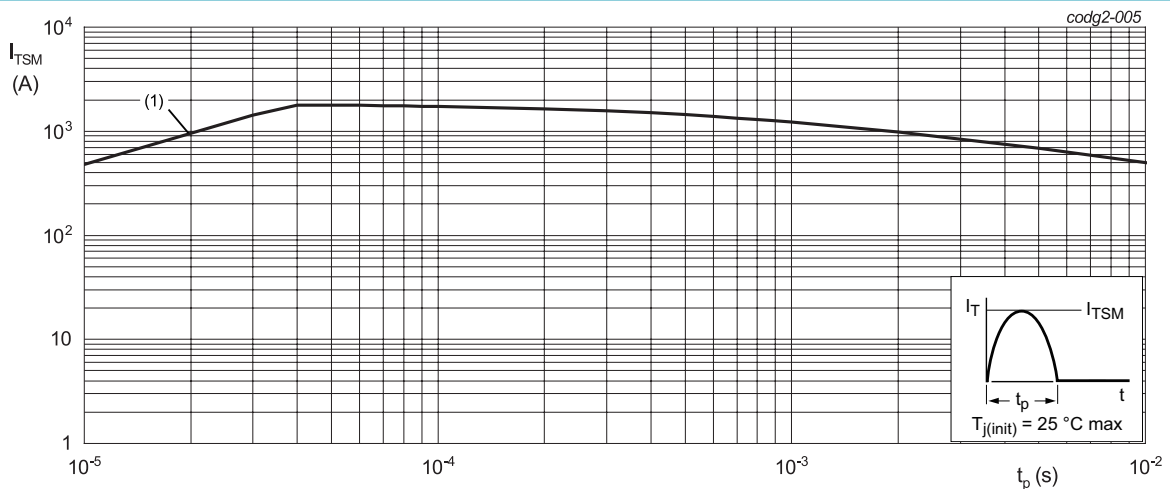
$\alpha$  = conduction angle  
 $a$  = form factor =  $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$  ms  
 (1)  $di_T/dt$  limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse duration; maximum values

## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter   | Conditions            | Notes | Min | Typ | Max | Unit |
|----------------|---|-----------------------|-------|-----|-----|-----|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | <a href="#">Fig 6</a> |       | -   | -   | 1.3 | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       | in free air           |       | -   | 60  | -   | K/W  |

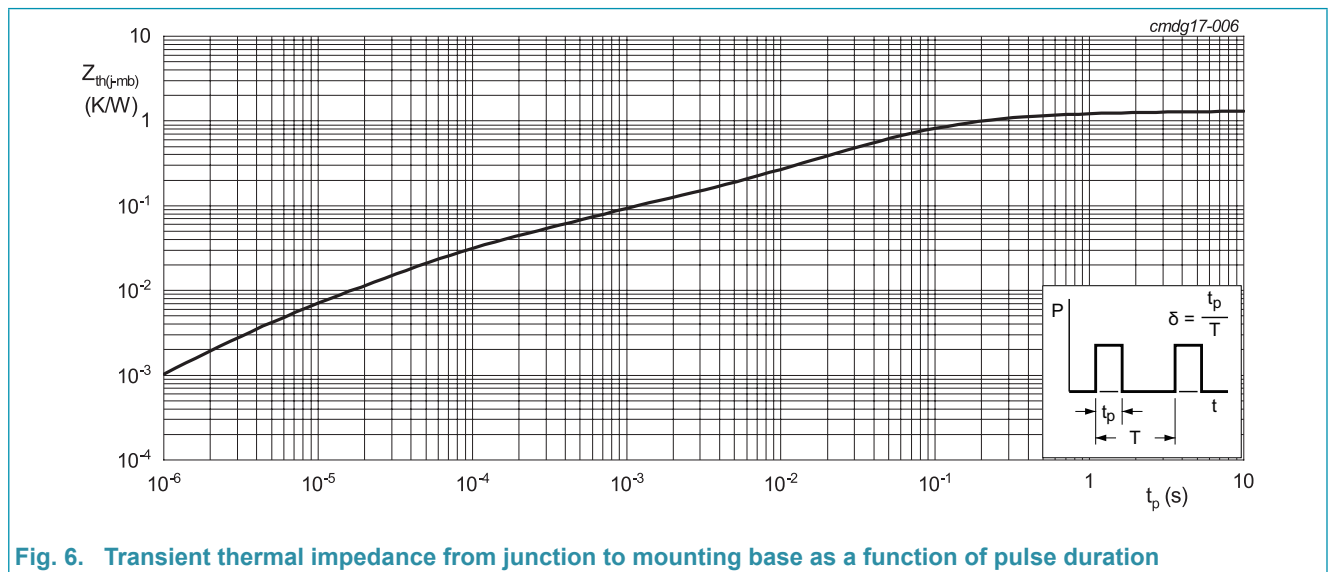


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 10. Isolation characteristics

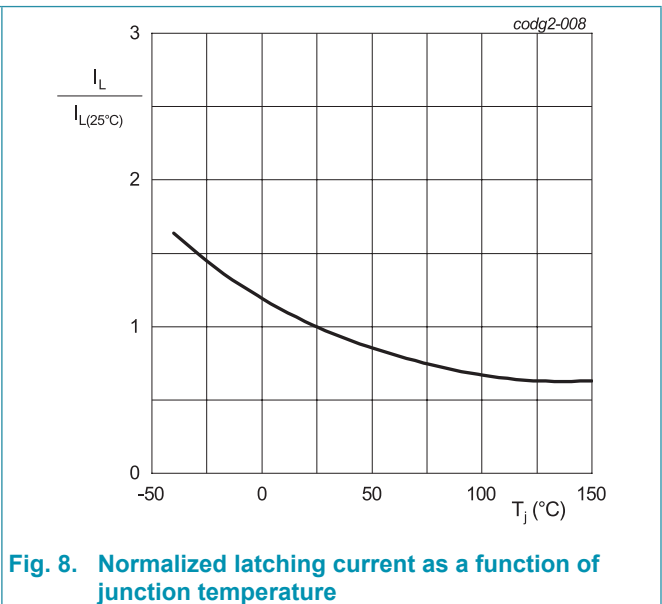
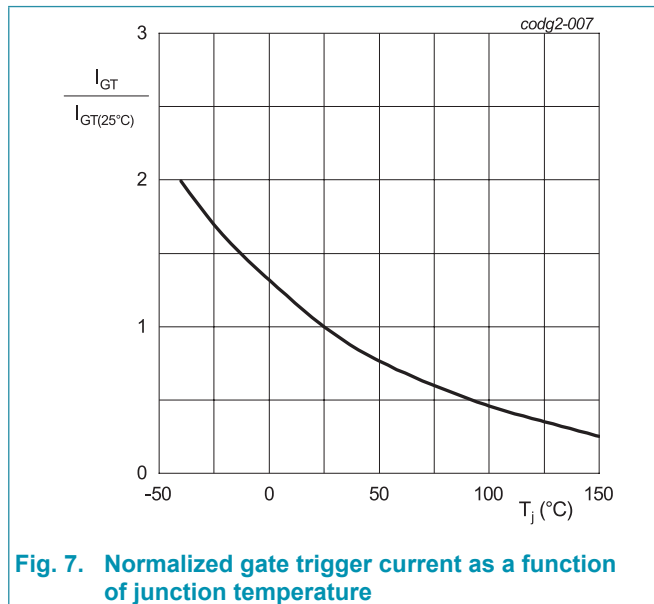
Table 7. Isolation characteristics

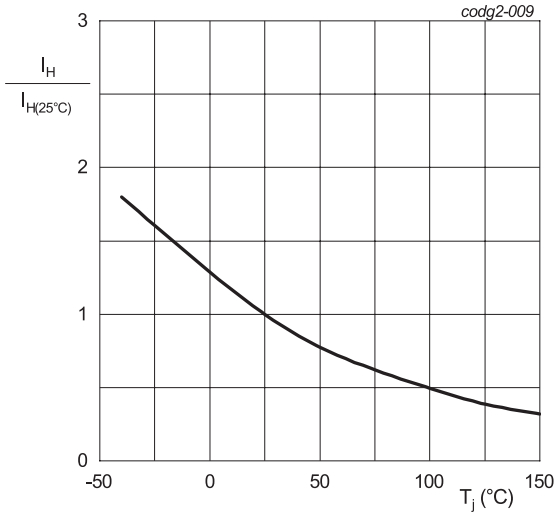
| Symbol          | Parameter             | Conditions  | Notes | Min | Typ | Max  | Unit |
|-----------------|-----------------------|---|-------|-----|-----|------|------|
| $V_{isol(RMS)}$ | RMS isolation voltage | 50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free |       | -   | -   | 2500 | V    |
| $C_{isol}$      | isolation capacitance | from cathode to external heatsink   |       | -   | 10  | -    | pF   |

## 11. Characteristics

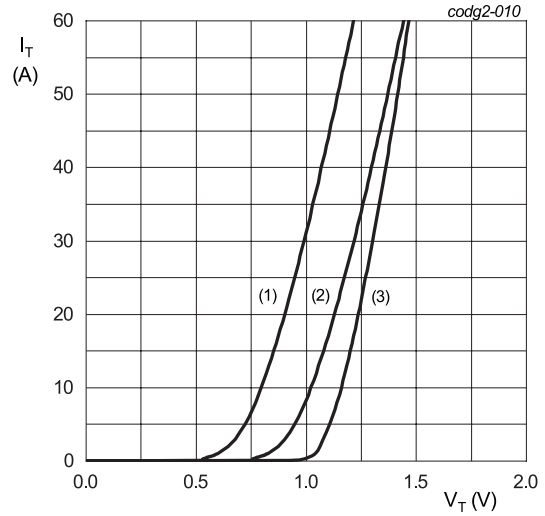
Table 8. Characteristics

| Symbol                         | Parameter                         | Conditions  | Notes | Min  | Typ | Max  | Unit             |
|--------------------------------|-----------------------------------|---|-------|------|-----|------|------------------|
| <b>Static characteristics</b>  |                                   |   |       |      |     |      |                  |
| $I_{GT}$                       | gate trigger current              | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 7</a>  |       | -    | -   | 15   | mA               |
| $I_L$                          | latching current                  | $V_D = 12\text{ V}$ ; $I_G = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 8</a>  |       | -    | -   | 80   | mA               |
| $I_H$                          | holding current                   | $V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>   |       | -    | -   | 60   | mA               |
| $V_T$                          | on-state voltage                  | $I_T = 100\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>   |       | -    | -   | 1.65 | V                |
| $V_{GT}$                       | gate trigger voltage              | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 11</a>   |       | -    | 0.7 | 1.2  | V                |
|                                |                                   | $V_D = 800\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_j = 150\text{ °C}$   |       | 0.25 | 0.5 | -    | V                |
| $I_D$                          | off-state current                 | $V_D = 800\text{ V}$ ; $T_j = 25\text{ °C}$   |       | -    | -   | 5    | $\mu\text{A}$    |
|                                |                                   | $V_D = 800\text{ V}$ ; $T_j = 150\text{ °C}$  |       | -    | -   | 2    | mA               |
| $I_R$                          | reverse current                   | $V_D = 800\text{ V}$ ; $T_j = 25\text{ °C}$   |       | -    | -   | 5    | $\mu\text{A}$    |
|                                |                                   | $V_D = 800\text{ V}$ ; $T_j = 150\text{ °C}$  |       | -    | -   | 2    | mA               |
| <b>Dynamic characteristics</b> |                                   |   |       |      |     |      |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage | $V_{DM} = 536\text{ V}$ ; $T_j = 150\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                         |       | 500  | -   | -    | V/ $\mu\text{s}$ |
| $t_{gt}$                       | gate-controlled turn-on time      | $I_{TM} = 50\text{ A}$ ; $V_D = 800\text{ V}$ ; $I_G = 30\text{ mA}$ ; $dI_G/dt = 5\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$                    |       | -    | 2   | -    | $\mu\text{s}$    |
| $t_q$                          | commutated turn-off time          | $I_{TM} = 2\text{ A}$ ; $t_p = 50\text{ }\mu\text{s}$ ; $dV/dt = 5\text{ V}/\mu\text{s}$ ; $dI/dt = 30\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$ |       | -    | -   | 25   | $\mu\text{s}$    |



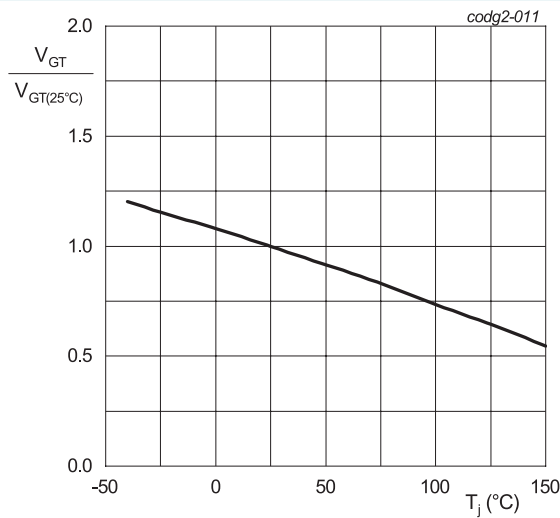


**Fig. 9. Normalized holding current as a function of junction temperature**



$V_o = 1.006 \text{ V}; R_s = 0.0073 \Omega$   
 (1)  $T_j = 150 \text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 150 \text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

**Fig. 10. On-state current as a function of on-state voltage**

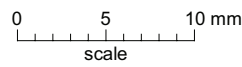
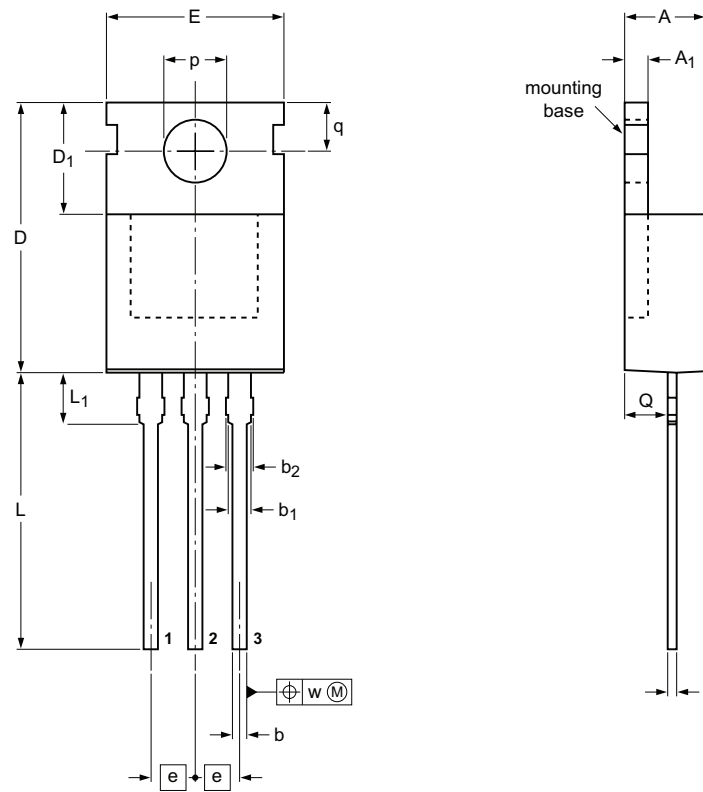


**Fig. 11. Normalized gate trigger voltage as a function of junction temperature**

## 12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220

SOT78D



DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub> | b          | b <sub>1</sub> | b <sub>2</sub> | c          | D            | D <sub>1</sub><br>ref | E           | e    | L            | L <sub>1</sub><br>ref | p          | Q          | q          | w   |
|------|------------|----------------|------------|----------------|----------------|------------|--------------|-----------------------|-------------|------|--------------|-----------------------|------------|------------|------------|-----|
| mm   | 4.7<br>4.3 | 1.40<br>1.25   | 0.9<br>0.6 | 1.4<br>1.1     | 1.72<br>1.32   | 0.6<br>0.4 | 16.0<br>15.2 | 6.5                   | 10.3<br>9.7 | 2.54 | 14.0<br>12.8 | 3.0                   | 3.7<br>3.5 | 2.6<br>2.2 | 3.0<br>2.7 | 0.2 |

| OUTLINE<br>VERSION | REFERENCES |        |       |  | EUROPEAN<br>PROJECTION | ISSUE DATE           |
|--------------------|------------|--------|-------|--|------------------------|----------------------|
|                    | IEC        | JEDEC  | JEITA |  |                        |                      |
| SOT78D             |            | TO-220 |       |  |                        | 07-04-04<br>07-07-10 |



## 13. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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## 14. Contents

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|                                     |    |
|-------------------------------------|----|
| 1. General description.....         | 1  |
| 2. Features and benefits .....      | 1  |
| 3. Applications .....               | 1  |
| 4. Quick reference data.....        | 1  |
| 5. Pinning information.....         | 2  |
| 6. Ordering information.....        | 2  |
| 7. Marking.....                     | 2  |
| 8. Limiting values .....            | 3  |
| 9. Thermal characteristics .....    | 5  |
| 10. Isolation characteristics ..... | 5  |
| 11. Characteristics.....            | 6  |
| 12. Package outline .....           | 8  |
| 13. Legal information .....         | 9  |
| 14. Contents .....                  | 11 |

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